

MECHANICAL CASE OUTLINE

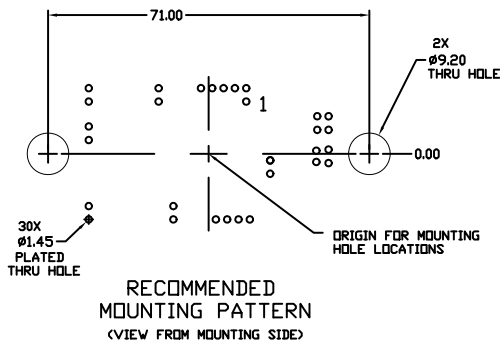
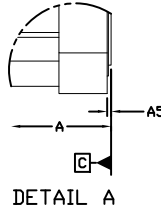
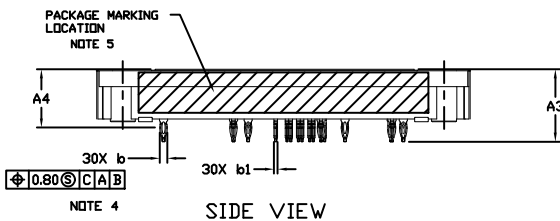
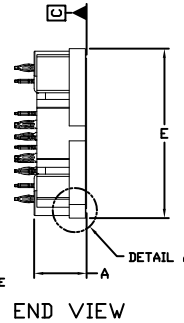
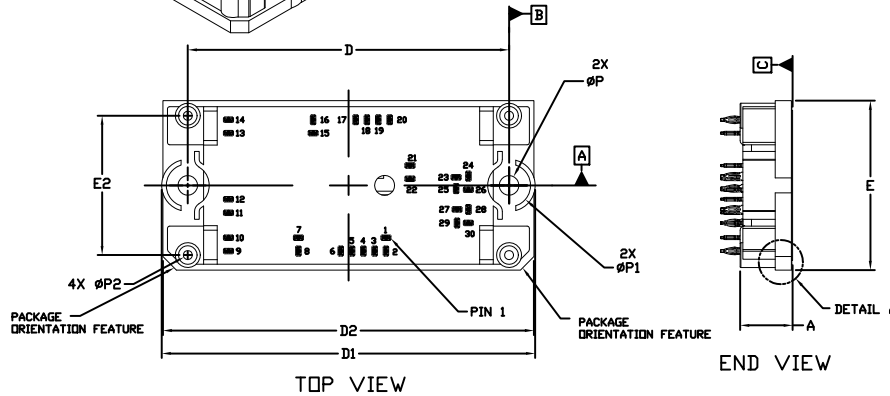
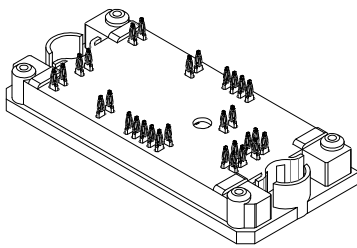
PACKAGE DIMENSIONS

ON Semiconductor®



PIM30, 71x37.4
CASE 180AD
ISSUE E

DATE 28 NOV 2017



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSIONS b AND b1 APPLY TO THE PLATED TERMINALS AND ARE MEASURED AT DIMENSION A4.
- POSITION OF THE CENTER OF THE TERMINALS IS DETERMINED FROM DATUM B THE CENTER OF DIMENSION D, X DIRECTION, AND FROM DATUM A, Y DIRECTION. POSITIONAL TOLERANCE, AS NOTED IN DRAWING, APPLIES TO EACH TERMINAL IN BOTH DIRECTIONS.
- PACKAGE MARKING IS LOCATED AS SHOWN ON THE SIDE OPPOSITE THE PACKAGE ORIENTATION FEATURES.

MOUNTING HOLE POSITION			MOUNTING HOLE POSITION		
PIN	X	Y	PIN	X	Y
1	8.30	11.55	16	-7.800	-14.50
2	8.30	14.50	17	1.60	-14.50
3	5.80	14.50	18	4.10	-14.50
4	3.30	14.50	19	6.60	-14.50
5	0.80	14.50	20	9.10	-14.50
6	-1.70	14.50	21	13.60	-4.40
7	-11.05	11.55	22	13.60	-1.45
8	-11.05	14.50	23	23.80	-1.80
9	-26.50	14.50	24	26.50	-2.05
10	-26.50	11.55	25	23.80	0.70
11	-26.50	6.05	26	26.50	0.95
12	-26.50	3.05	27	24.00	5.30
13	-26.50	-11.55	28	26.50	5.30
14	-26.50	-14.50	29	24.00	8.30
15	-7.80	-11.55	30	26.50	8.30

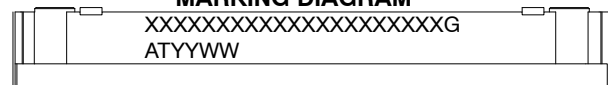
NOTE 4

DIM	MILLIMETERS	
	MIN.	NDM.
A	11.10	12.10
A3	15.50	16.50
A4	12.88	BSC
A5	0.00	0.45
b	1.61	1.71
b1	0.75	0.85
D	70.50	71.50
D1	82.00	83.00
D2	81.50	82.50
E	36.90	37.90
E2	30.30	31.30
P	4.30	4.50
P1	9.30	9.70
P2	1.90	2.10

PIN	PIN POSITION		PIN	PIN POSITION	
	X	Y		X	Y
1	8.30	-11.55	16	-7.800	14.50
2	8.30	-14.50	17	1.60	14.50
3	5.80	-14.50	18	4.10	14.50
4	3.30	-14.50	19	6.60	14.50
5	0.80	-14.50	20	9.10	14.50
6	-1.70	-14.50	21	13.60	4.40
7	-11.05	-11.55	22	13.60	1.45
8	-11.05	-14.50	23	23.80	1.80
9	-26.50	-14.50	24	26.50	2.05
10	-26.50	-11.55	25	23.80	-0.70
11	-26.50	-6.05	26	26.50	-0.95
12	-26.50	-3.05	27	24.00	-5.30
13	-26.50	11.55	28	26.50	-5.30
14	-26.50	14.50	29	24.00	-8.30
15	-7.80	11.55	30	26.50	-8.30

GENERIC

MARKING DIAGRAM*



XXXXX = Specific Device Code
G = Pb-Free Package
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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